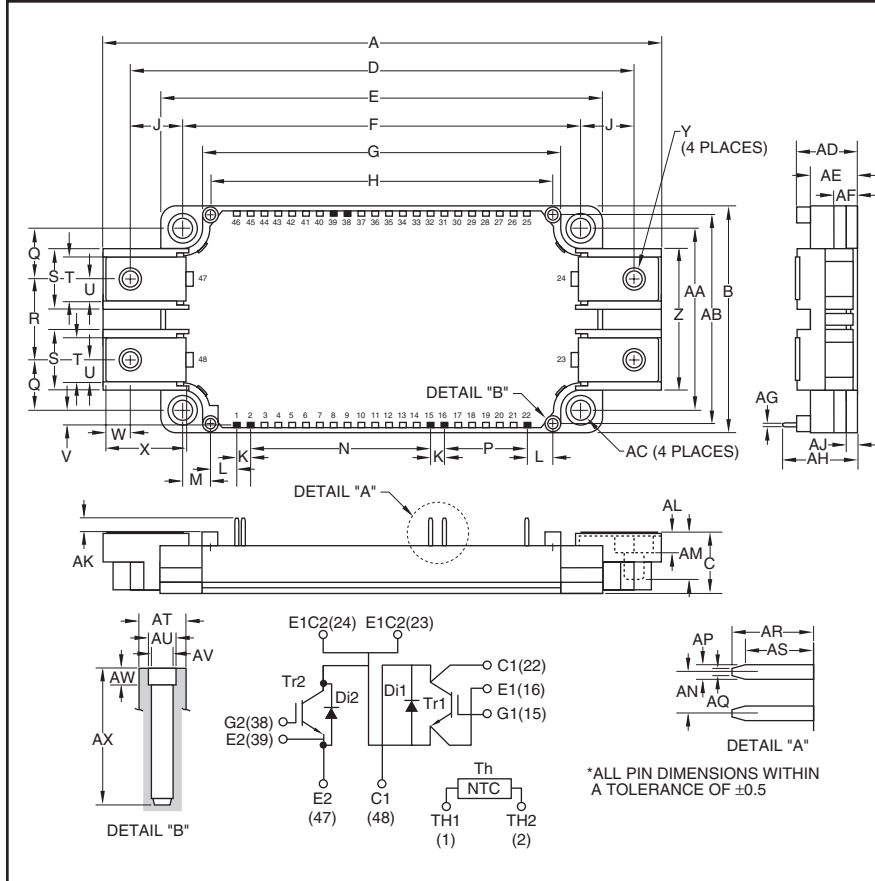


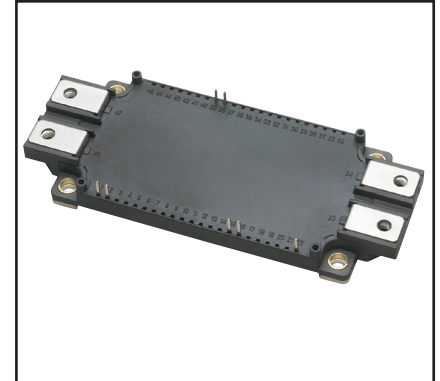
### Dual IGBTMOD™ NX-S Series Module 300 Amperes/1200 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	5.98	152.0
B	2.44	62.0
C	0.67	17.0
D	5.39	137.0
E	4.79	121.7
F	4.33±0.02	110.0±0.5
G	3.89	99.0
H	3.72	94.5
J	0.53	13.5
K	0.15	3.8
L	0.28	7.25
M	0.30	7.75
N	1.95	49.54
P	0.9	22.86
Q	0.55	14.0
R	0.87	22.0
S	0.67	17.0
T	0.48	12.0
U	0.24	6.0
V	0.16	4.2
W	0.37	6.5
X	0.83	21.14
Y	M6	M6

Dimensions	Inches	Millimeters
Z	1.53	39.0
AA	1.97±0.02	50.0±0.5
AB	2.26	57.5
AC	0.22 Dia.	5.5 Dia.
AD	0.67+0.04/-0.02	17.0+1.0/-0.5
AE	0.51	13.0
AF	0.27	7.0
AG	0.03	0.8
AH	0.81	20.5
AJ	0.12	3.0
AK	0.14	3.5
AL	0.21	5.4
AM	0.49	12.5
AN	0.15	3.81
AP	0.05	1.15
AQ	0.025	0.65
AR	0.29	7.4
AS	0.24	6.2
AT	0.17 Dia.	4.3 Dia.
AU	0.10 Dia.	2.5 Dia.
AV	0.08 Dia.	2.1 Dia.
AW	0.06	1.5
AX	0.49	12.5



#### Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of two IGBT Transistors in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

#### Features:

- Low Drive Power
- Low  $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

#### Applications:

- AC Motor Control
- Motion/Servo Control
- Photovoltaic/Fuel Cell

#### Ordering Information:

Example: Select the complete module number you desire from the table below -i.e. CM300DX-24S is a 1200V ( $V_{CES}$ ), 300 Ampere Dual IGBTMOD™ Power Module.

Type	Current Rating Amperes	$V_{CES}$ Volts (x 50)
CM	300	24

**CM300DX-24S**  
**Dual IGBTMOD™ NX-S Series Module**  
 300 Amperes/1200 Volts

**Absolute Maximum Ratings,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	CM300DX-24S	Units
Maximum Junction Temperature	$T_{j(\max)}$	+175	$^\circ\text{C}$
Operating Power Device Junction Temperature	$T_{j(\text{op})}$	-40 to 150	$^\circ\text{C}$
Storage Temperature	$T_{\text{stg}}$	-40 to 125	$^\circ\text{C}$
Mounting Torque, M5 Mounting Screws	—	31	in-lb
Mounting Torque, M6 Main Terminal Screws	—	40	in-lb
Module Weight (Typical)	—	330	Grams
Isolation Voltage (Terminals to Baseplate, $f = 60\text{Hz}$ , AC 1 minute)	$V_{\text{ISO}}$	2500	$V_{\text{rms}}$

**Inverter Sector**

Collector-Emitter Voltage ( $V_{\text{GE}} = 0\text{V}$ )	$V_{\text{CES}}$	1200	Volts
Gate-Emitter Voltage ( $V_{\text{CE}} = 0\text{V}$ )	$V_{\text{GES}}$	$\pm 20$	Volts
Collector Current (DC, $T_C = 119^\circ\text{C}$ )*1,*5	$I_C$	300	Amperes
Collector Current (Pulse)*4	$I_{\text{CRM}}$	600	Amperes
Total Power Dissipation ( $T_C = 25^\circ\text{C}$ )*1,*5	$P_{\text{tot}}$	2270	Watts
Emitter Current, Free Wheeling Diode Forward Current ( $T_C = 25^\circ\text{C}$ )*1,*5	$I_E^{*3}$	300	Amperes
Emitter Current, Free Wheeling Diode Forward Current (Pulse)*4	$I_{\text{ERM}}^{*3}$	600	Amperes

\*1 Case temperature ( $T_C$ ) and heatsink temperature ( $T_j$ ) measured point is just under the chips.

\*3 Represent ratings and characteristics of the anti-parallel, emitter-to-collector free wheeling diode (FWDi).

\*4 Pulse width and repetition rate should be such that device junction temperature ( $T_j$ ) does not exceed  $T_{j(\max)}$  rating.

\*5 Junction temperature ( $T_j$ ) should not increase beyond maximum junction temperature ( $T_{j(\max)}$ ) rating.

**CM300DX-24S**  
**Dual IGBTMOD™ NX-S Series Module**  
 300 Amperes/1200 Volts

**Electrical and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

**Inverter Sector**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units	
Collector Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	1	mA	
Gate Leakage Current	$I_{GES}$	$\pm V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	0.5	$\mu\text{A}$	
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 30\text{mA}, V_{CE} = 10V$	5.4	6	6.6	Volts	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$ (Chip)	$I_C = 300\text{A}, V_{GE} = 15V, T_j = 25^\circ\text{C}$	—	1.7	2.15	Volts	
		$I_C = 300\text{A}, V_{GE} = 15V, T_j = 125^\circ\text{C}$	—	1.9	—	Volts	
		$I_C = 300\text{A}, V_{GE} = 15V, T_j = 150^\circ\text{C}$	—	1.95	—	Volts	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$ (Terminal)	$I_C = 300\text{A}, V_{GE} = 15V, T_j = 25^\circ\text{C}^{*6}$	—	1.85	2.3	Volts	
		$I_C = 300\text{A}, V_{GE} = 15V, T_j = 125^\circ\text{C}^{*6}$	—	2.05	—	Volts	
		$I_C = 300\text{A}, V_{GE} = 15V, T_j = 150^\circ\text{C}^{*6}$	—	2.1	—	Volts	
Input Capacitance	$C_{ies}$		—	—	30	nF	
Output Capacitance	$C_{oes}$	$V_{GE} = 0V, V_{CE} = 10V$	—	—	6.0	nF	
Reverse Transfer Capacitance	$C_{res}$		—	—	0.50	nF	
Total Gate Charge	$Q_G$	$V_{CC} = 600V, I_C = 300\text{A}, V_{GE} = 15V$	—	700	—	nC	
Inductive Load	Turn-on Delay Time	$t_{d(on)}$	—	—	800	ns	
	Turn-on Rise Time	$t_r$	$V_{CC} = 600V, I_C = 300\text{A}, ^{*7}$	—	—	200	ns
	Turn-off Delay Time	$t_{d(off)}$	$V_{GE} = \pm 15V,$	—	—	600	ns
	Turn-off Fall Time	$t_f$	$R_G = 2.7\Omega, \text{ Inductive Load},$	—	—	300	ns
Reverse Recovery Time	$t_{rr}^{*3}$	$I_E = 300\text{A}$	—	—	300	ns	
Reverse Recovery Charge	$Q_{rr}^{*3}$		—	16	—	$\mu\text{C}$	
Turn-on Switching Loss per Pulse	$E_{on}$	$V_{CC} = 600V, I_C (I_E) = 300\text{A}, ^{*7}$	—	48	—	mJ	
Turn-off Switching Loss per Pulse	$E_{off}$	$V_{GE} = \pm 15V, R_G = 2.7\Omega,$	—	32	—	mJ	
Reverse Recovery Loss per Pulse	$E_{rec}^{*3}$	$T_j = 150^\circ\text{C}, \text{ Inductive Load}$	—	18	—	mJ	
Emitter-Collector Voltage	$V_{EC}^{*3}$ (Chip)	$I_E = 300\text{A}, V_{GE} = 0V, T_j = 25^\circ\text{C}$	—	1.7	2.15	Volts	
		$I_E = 300\text{A}, V_{GE} = 0V, T_j = 125^\circ\text{C}$	—	1.7	—	Volts	
		$I_E = 300\text{A}, V_{GE} = 0V, T_j = 150^\circ\text{C}$	—	1.7	—	Volts	
Emitter-Collector Voltage	$V_{EC}^{*3}$ (Terminal)	$I_E = 300\text{A}, V_{GE} = 0V, T_j = 25^\circ\text{C}^{*6}$	—	1.85	2.3	Volts	
		$I_E = 300\text{A}, V_{GE} = 0V, T_j = 125^\circ\text{C}^{*6}$	—	1.85	—	Volts	
		$I_E = 300\text{A}, V_{GE} = 0V, T_j = 150^\circ\text{C}^{*6}$	—	1.85	—	Volts	

**Thermal and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case <sup>*1</sup>	$R_{th(j-c)Q}$	Per IGBT	—	—	0.66	K/W
Thermal Resistance, Junction to Case <sup>*1</sup>	$R_{th(j-c)D}$	Per FWDi	—	—	0.12	K/W
Internal Gate Resistance	$r_g$	Per Switch	—	6.5	—	$\Omega$

<sup>\*1</sup> Case temperature ( $T_C$ ) and heatsink temperature ( $T_H$ ) measured point is just under the chips.

<sup>\*3</sup> Represent ratings and characteristics of the anti-parallel, emitter-to-collector free wheeling diode (FWDi).

<sup>\*6</sup> Pulse width and repetition rate should be such as to cause negligible temperature rise.

<sup>\*7</sup> Recommended maximum collector supply voltage  $V_{CC}$  is  $800V_{dc}$ .

**CM300DX-24S**  
**Dual IGBTMOD™ NX-S Series Module**  
 300 Amperes/1200 Volts

**NTC Thermistor Sector, T<sub>j</sub> = 25°C unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Zero Power Resistance	R	T <sub>C</sub> = 25°C	4.85	5.00	5.15	kΩ
Deviation of Resistance	ΔR/R	T <sub>C</sub> = 100°C, R <sub>100</sub> = 493Ω	-7.3	—	+7.8	%
B Constant	B <sub>(25/50)</sub>	Approximate by Equation <sup>9</sup>	—	3375	—	K
Power Dissipation	P <sub>25</sub>	T <sub>C</sub> = 25°C	—	—	10	mW

**Module, T<sub>j</sub> = 25°C unless otherwise specified**

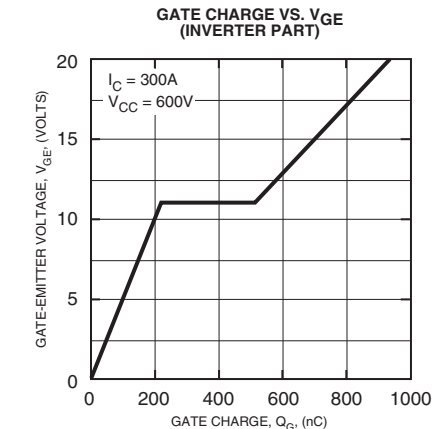
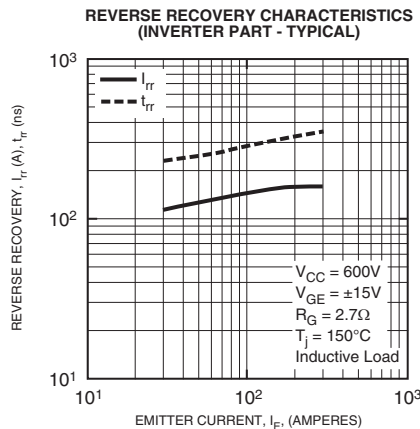
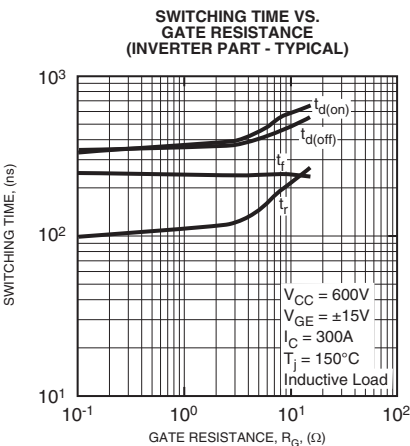
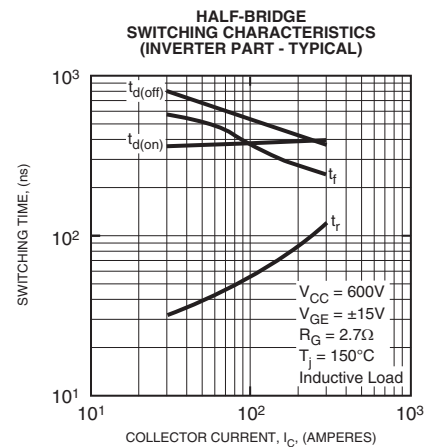
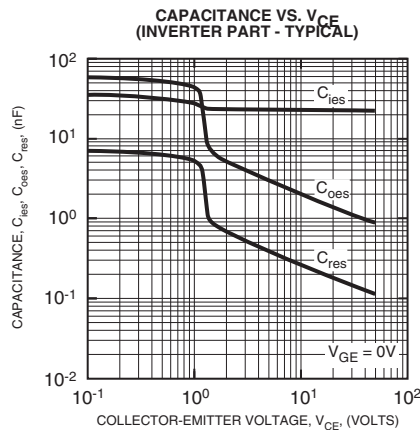
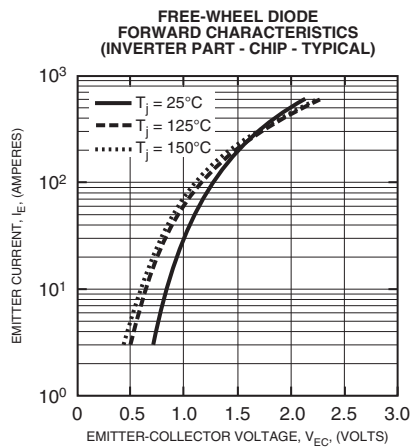
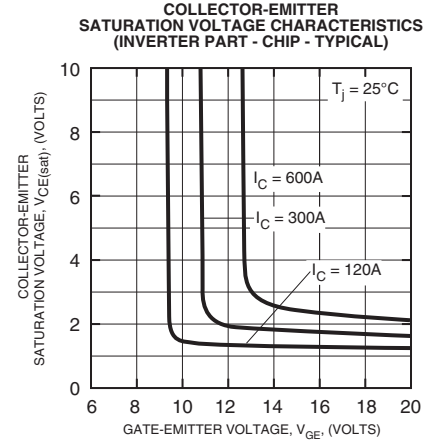
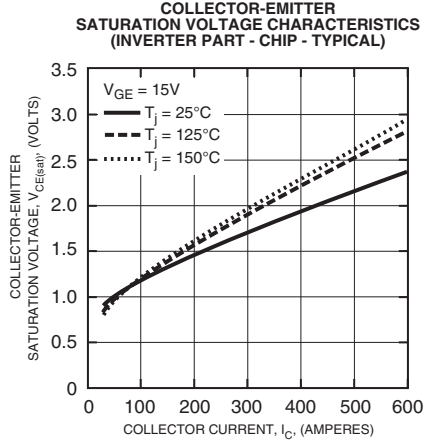
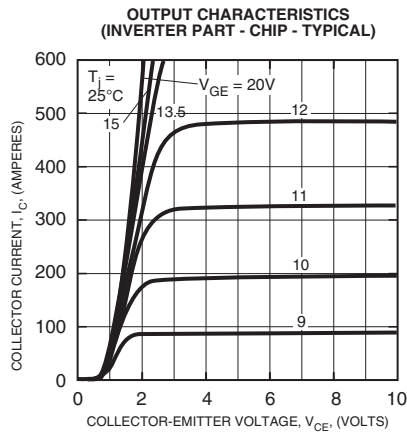
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Lead Resistance (Main Terminals-Chip)	R <sub>lead</sub>	T <sub>C</sub> = 25°C (Per Switch)	—	—	0.9	mΩ
Contact Thermal Resistance <sup>*1</sup> (Case to Heatsink)	R <sub>th(c-f)</sub>	Thermal Grease Applied (Per 1 Module) <sup>*2</sup>	—	0.015	—	K/W

\*1 Case temperature (T<sub>C</sub>) and heatsink temperature (T<sub>f</sub>) measured point is just under the chips.

\*2 Typical value is measured by using thermally conductive grease of λ = 0.9 [W/(m • K)].

\*9  $B_{(25/50)} = \ln\left(\frac{R_{25}}{R_{50}}\right) / \left(\frac{1}{T_{25}} - \frac{1}{T_{50}}\right)$  R<sub>25</sub>: Resistance at Absolute Temperature T<sub>25</sub> [K], R<sub>50</sub>: resistance at Absolute Temperature T<sub>50</sub> [K],  
 T<sub>25</sub> = 25 [°C] + 273.15 = 298.15 [K], T<sub>50</sub> = 50 [°C] + 273.15 = 323.15 [K]

**CM300DX-24S**  
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 300 Amperes/1200 Volts



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